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## News Release

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### **RADVISION Selects Texas Instruments High Performance DSP for New Feature-Rich Videoconferencing Solution**

New ViaIP™ Multipoint Conferencing Unit and Multimedia Video Processor (MVP) Card Leverages TI's DSP Programmability to Offer Powerful Real-Time Multimedia Processing

DALLAS (June 5, 2003) -- Texas Instruments (NYSE: TXN) (TI) today announced that RADVISION (Nasdaq: RVSN) chose TI's advanced TMS320C6000™ programmable digital signal processors (DSPs) to power its new MVP media processor board, a key component of the company's recently announced Multimedia Control Unit (MCU) version 3.

The MCU v3 is the company's flagship solution for videoconferencing and rich media communications for enterprises, institutions and service providers.

The new board, driven by twelve programmable, high-performance TI TMS320C6203 DSPs, provides a total of 28.8 GIPS (Giga Instructions per Second) and can support up to 100 simultaneous ports/users in real-time videoconferencing over traditional IP (H.323), ISDN (H.320), SIP and 3G video telephony (3G-324M).

New features delivered by the MCU v3, when operated with the TI chips, include a processing system with unparalleled power and advanced features, functionality and quality for both video and audio signals. Examples of these new processor-enabled features include:

- bandwidth optimization (Quality of Service);
- discrete conference stream to each end point depending on user settings and system capabilities;
- H.261 to H.263 transcoding, frame rate and resolution transcoding;
- advanced speed matching and support of the G.722.1 voice compression algorithm which provides the best standards-based audio stream possible with minimal bandwidth overhead (8 – 16 Kbps vs. 64 Kbps).

Additionally, by virtue of the company's use of programmable TI DSPs, the platform is software upgradeable and will dynamically support new compression algorithms, such as H.264, as they are ratified. This is in stark contrast to using custom-designed voice and video chips which are not upgradeable but rather have hard-wired functionality embedded in silicon, requiring a new chipset to implement new technology requirements.

"We are delighted that RADVISION has selected our high-performance, programmable DSPs as the perfect fit for their videoconferencing over IP solution," said Jean-Marc Charpentier, European DSP platform business development manager, Texas Instruments. "The fully upward code-compatibility of our DSPs means that systems can be easily moved to more powerful DSPs as they become available, without having to rewrite code, thus preserving initial investment and reducing development efforts for applications."

With the new MVP media processor based on the TI chip, the RADVISION MCU v3 also delivers a host of new layout options, including an increased number of continuous presence options, unique high quality picture in picture layout, zoom in on active speaker, dynamic layout where the display adjusts as people leave/join the conference, color highlight of active speaker and text identification of speakers. The system also features a lecture mode by which an instructor can view multiple students in auto-switching mode on the screen while students see only the instructor.

"Programmability and scalability of DSPs are crucial elements in developing this powerful videoconferencing media processor, so it was highly important to partner with the right chip manufacturer," said Avinoam Barak, general manager, of RADVISION's Networking Business Unit. "By using TI's TMS320C62x™ generation and eXpressDSP™ software and development tools, we give our customers a powerful media experience that also provides the full forward and backwards software compatibility, enabling us to easily up grade our products in the future to new TI DSPs, ensuring that our visual communications continue to seamlessly evolve as technology does."

**About RADVISION MCU v3 and MVP Media Processing Board**

RADVISION's new MCU version 3 fully leverages the programmability and scalability of the twelve TI C6203 DSPs running at the heart of the system to offer a variety of original features for dedicated videoconferencing processors. Featuring major advancements in supporting emerging protocols (SIP and 3G-324M), end points (Tandberg DuoVideo and Microsoft® Windows® Messenger), and delivering advanced processing, screen layouts, data collaboration and call management, the new MCU v3 represents an industry breakthrough in videoconferencing with support for emerging standards, new features and high-quality media processing.

RADVISION's viaIP™ family offers a complete set of multipoint conferencing units, data collaboration, gateways, utilities and applications for rich media collaborative communications in large-scale enterprise, carrier and distributed network deployments. With mix and match flexibility, Radvision viaIP™ offers customers the applications and functionality to build the most suitable real-time collaborative conferencing configuration.

The RADVISION MCU v3, and the new MVP multimedia processor card, based on TI advanced DSPs, will both be available at the end of the second quarter of 2003.

**About TI's DSP Platform**

TI's TMS320C6000™ DSP platform includes a wide range of devices that raise the bar in performance, set new levels of cost efficiency and on-chip peripheral integration.

With performances ranging from 1200 to 5760 MIPS for fixed point and 600 to 1350 MFLOPS for floating-point, the C6000™ platform is optimized for designers working on targeted broadband infrastructure, high-performance audio and imaging applications. TI recently announced three new TMS320C64x™ DSP processors with record-breaking performance of 720 MHz as well as the roadmap to a performance of 1 GHz, opening the way for new, more powerful and more innovative high-speed processing applications. Hear RADVISION's plans for the new 1 GHz DSP at [www.ti.com/radvision1ghz](http://www.ti.com/radvision1ghz).

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#### **About RADVISION**

RADVISION (NASDAQ: RVSN) is the industry's leading provider of high quality, scalable and easy-to-use products and technologies for videoconferencing, video telephony, and the development of converged voice, video and data over IP and 3G networks. For more information please visit [www.radvision.com](http://www.radvision.com).

#### **About Texas Instruments**

Texas Instruments Incorporated provides innovative DSP and analog technologies to meet our customers' real world signal processing requirements. In addition to Semiconductor, the company's businesses include Sensors & Controls, and Educational & Productivity Solutions. TI is headquartered in Dallas, Texas, and has manufacturing, design or sales operations in more than 25 countries.

Texas Instruments is traded on the New York Stock Exchange under the symbol TXN. More information is located on the World Wide Web at [www.ti.com](http://www.ti.com).

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